

### AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions of claims in the application.

1. (Currently Amended): A mounting apparatus ~~for sticking a dicing tape to a ring frame having a semiconductor wafer disposed in an inside area of said ring frame~~, comprising:

supporting means for supporting a strip material including a film ~~corresponding to the dicing tape~~ stuck on a surface of a base sheet;

pre-cutting means for forming a cut in said film of said strip material fed from the supporting means, thereby forming a pre-cut portion of said film; ~~in accordance with the size of the ring frame, thereby forming the dicing tape~~;

a peeling means ~~plate~~ for peeling ~~said dicing tape~~ the pre-cut portion of said film from said base sheet, said peeling plate being located downstream of said pre-cutting means in the sheet feeding direction; and

a press roller positioned at a downstream end of said peeling means, ~~plate~~ in the sheet feeding direction, for pressing the pre-cut portion of said film on a substrate, ~~dicing tape onto the ring frame~~

wherein said pre-cutting means is configured such that the cut is made from a face of said film opposite the face of said film which is to be peeled from the base sheet by said peeling means, and

wherein said press roller is configured to press the pre-cut portion of said film on the face of said film opposite the face of said film peeled from the base sheet by said peeling means.

2. (Currently Amended): The mounting apparatus according to claim 1,

wherein a tension control means is disposed between said supporting means and said pre-cut means,

wherein the tension control means comprises a dancer roller, which is movable vertically so as to allow the strip material to be fed out toward said press roller ~~pressing means~~ while giving tension due to its own weight to said strip material, and first and second sensors for detecting a raised position and a lowered position of the dancer roller respectively, and

wherein, when the first sensor detects said dancer roller at the raised position, said supporting means feeds out the strip material by a predetermined amount to lower the dancer roller, and when the second sensor detects the dancer roller at the lowered position, said supporting means stops feeding out the strip material therefrom.

3. (Withdrawn): A mounting method in which a ring frame is disposed on a table, a semiconductor wafer is disposed in an inside area of the ring frame, and a dicing tape is stuck onto said ring frame to fix the semiconductor wafer to the ring frame, comprising the steps of:

forming a cut in said film in accordance with the size of said ring frame in a process of feeding out a strip material attaching a film for forming dicing tapes stuck on one surface of a base sheet;

peeling off the dicing tape formed inside said cut from the base sheet; and

moving the dicing tape and said table relative to each other to stick said dicing tape onto the semiconductor wafer and the ring frame, thereby fixing the semiconductor wafer to the ring frame.

4. (Withdrawn): The mounting method according to claim 3, wherein a tension control means is disposed between said supporting means and a pre-cut means, wherein,

the tension control means comprises a dancer roller, which is movable vertically so as to allow said strip material to be fed out toward said sticking means while giving tension due to its own weight to said strip material, and first and second sensors for detecting a raised position and a lowered position of the dancer roller respectively, and wherein,

the following operations are repeated; i.e., when the first sensor detects said dancer roller at the raised position, said supporting means feeds out the strip material of a predetermined amount to lower the dancer roller, and when the second sensor detects the dancer roller at the lowered position, said supporting means stops feeding out the strip material therefrom.

5. (New) The mounting apparatus of claim 1, wherein said pre-cutting means includes a die receiving plate and a die roller having a cutter blade formed on a roller.

6. (New) The mounting apparatus of claim 1, wherein said pre-cutting means includes a movable roller and a die plate having a circular blade formed thereon.

7. (New) The mounting apparatus of claim 1, wherein said pre-cutting means includes a die receiving plate and a blade disposed on a rotation member which is rotatable by a motor.